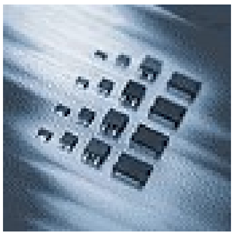

Material Content Data Sheet

RoHS

Halogen-Free

Sales Product Name	BSO080P03NS3E G	**Issued**	29. August 2013
MA#	MA000650830		
Package	PG-DSO-8-39	**Weight***	83.95 mg

Construction Element	**Material Group**	**Substances**	**CAS# if applicable**	**Weight [mg]**	**Average Mass [%]**	**Sum [%]**	**Average Mass [ppm]**	**Sum [ppm]**
chip	inorganic material	silicon	7440-21-3	2.479	2.95	2.95	29531	29531
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		122	
	non noble metal	zinc	7440-66-6	0.041	0.05		488	
	non noble metal	iron	7439-89-6	0.820	0.98		9762	
	non noble metal	copper	7440-50-8	33.276	39.64	40.68	396378	406750
wire	non noble metal	copper	7440-50-8	0.335	0.40	0.40	3994	3994
encapsulation	organic material	carbon black	1333-86-4	0.227	0.27		2702	
	plastics	epoxy resin	-	7.032	8.38		83763	
	inorganic material	silicondioxide	60676-86-0	38.108	45.39	54.04	453939	540404
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9694	9694
plating	noble metal	silver	7440-22-4	0.073	0.09	0.09	865	865
glue	plastics	epoxy resin	-	0.110	0.13		1314	
	noble metal	silver	7440-22-4	0.625	0.74	0.87	7448	8762
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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